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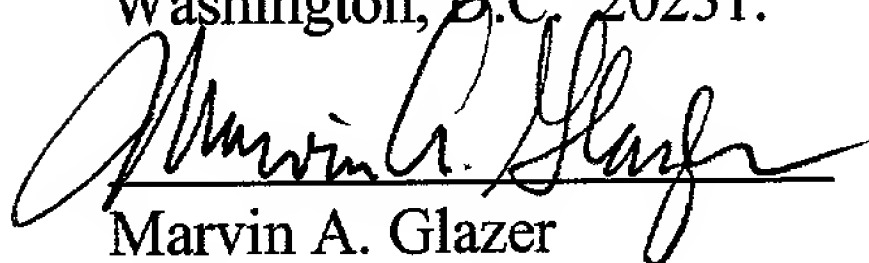
Docket No. 5833-A-13

Date January 22, 2001

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Marvin A. Glazer

January 22, 2001
Date

Box PATENT APPLICATION
Honorable Commissioner for Patents
Washington, D.C. 20231

Sir:

Transmitted herewith for filing is the patent application of

Inventors: Jamin Ling and Dave Charles Stepniak

For: "ELECTROLESS Ni/Pd/Au METALLIZATION STRUCTURE FOR COPPER INTERCONNECT SUBSTRATE AND METHOD THEREFOR"

Enclosed are:

- X 1 sheet of informal drawings
- X Declaration and Power of Attorney
- X Specification (incl. claims and abstract) 13 pages.

X Assignment

X Form PTO-1595 Recordation Form Cover Sheet

CLAIMS AS FILED

Total
Claims 24 - 20 = 4 x \$18.00 = \$ 72.00

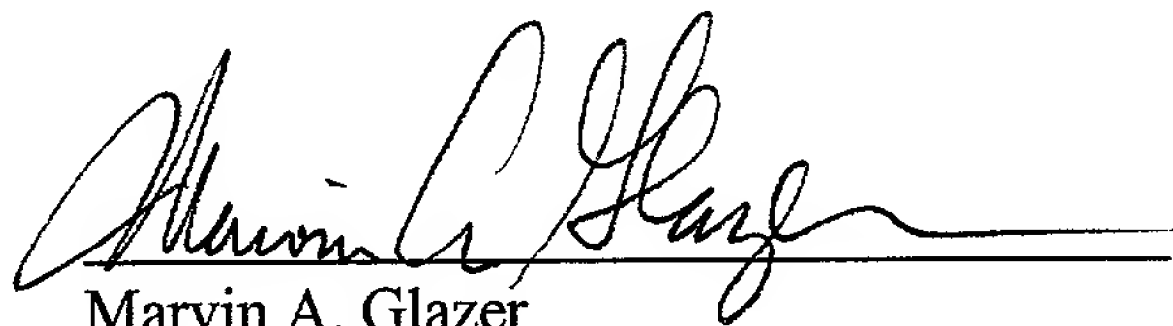
Independent
Claims 2 - 3 = 0 x \$80.00 = -0-

Basic Fee: \$710.00

Total Filing Fee: \$782.00

X The Commissioner is hereby authorized to charge any additional fees which may be required by this paper to Deposit Account No. 03-0088 and to credit any overpayment to this Deposit Account. Two (2) duplicate copies of this sheet are enclosed.

X A check in the amount of \$822.00 to cover the filing fee and the recordation fee (if needed) is enclosed.



Marvin A. Glazer

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